



Effects of Cooling Holes on SiC/SiC Strength and Durability

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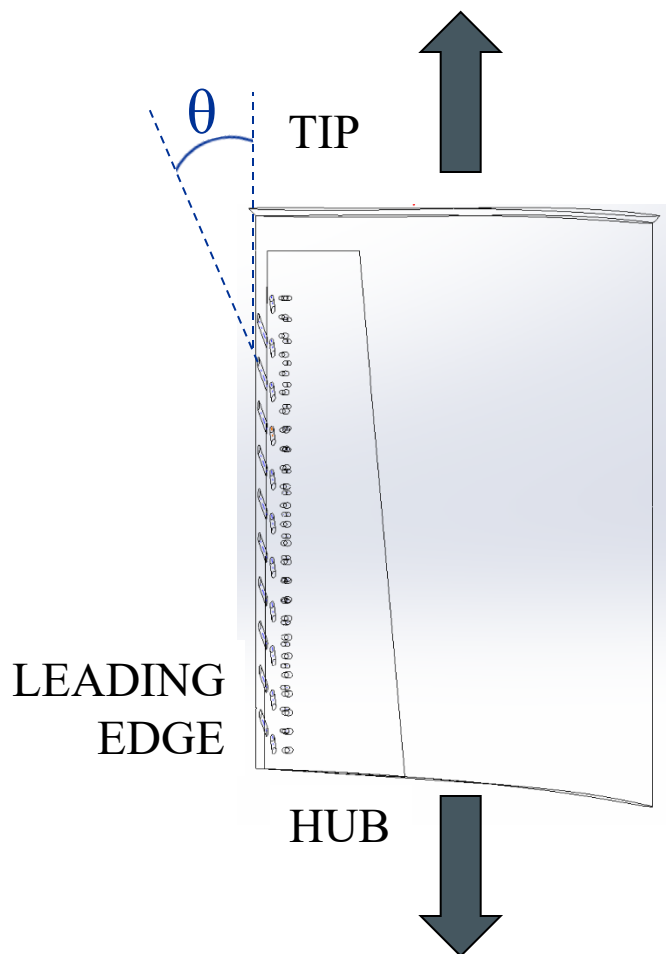
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This work was funded by the NASA Advanced Air Transport Technology (AATT) and Hybrid Thermally Efficient Core (HyTEC) Projects

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Background

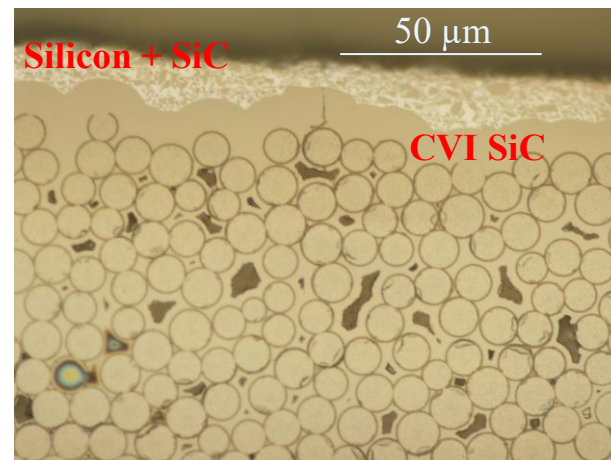


- CMC turbine engine components made from SiC/SiC provide an efficiency increase compared to superalloys, primarily as a result of decreased cooling requirements and decreased density.
- CMC components such as blades may still require film cooling.
- CMCs are known to be notch insensitive.
- The durability of SiC/SiC with cooling hole arrays is not well documented.
- This project seeks to understand the knockdown of matrix cracking strength due to multiple holes.

Materials

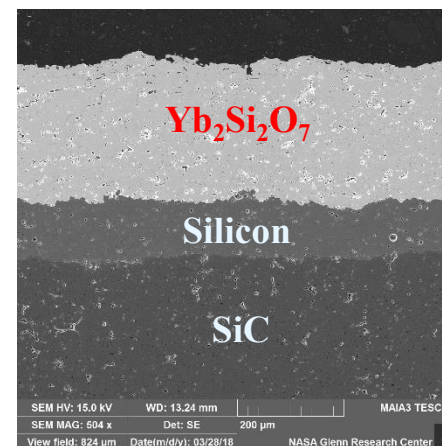
- Slurry MI material (NASA N24A) was used in this study

- 2D woven Sylramic iBN fibers
- Balanced architecture
- BN interphase
- CVI SiC
- Slurry MI Silicon
- Made by GE



- Some samples were coated with an EBC prior to drilling.

- Samples were grit blasted prior to coating
- Silicon bond coat
- $\text{Yb}_2\text{Si}_2\text{O}_7$ (Gen 2) top coat

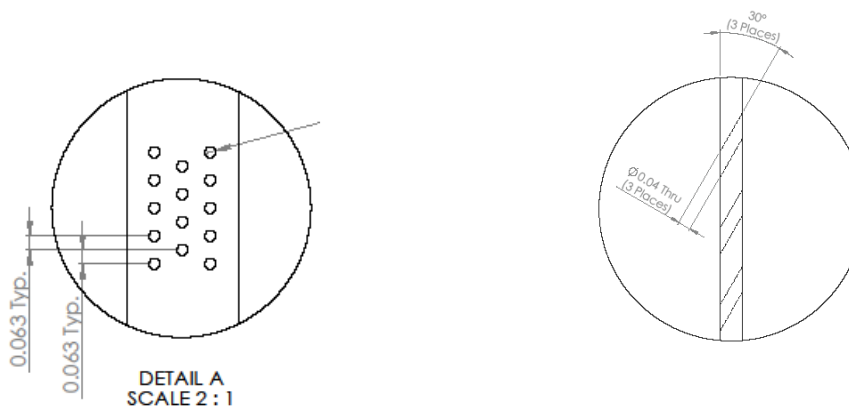


From
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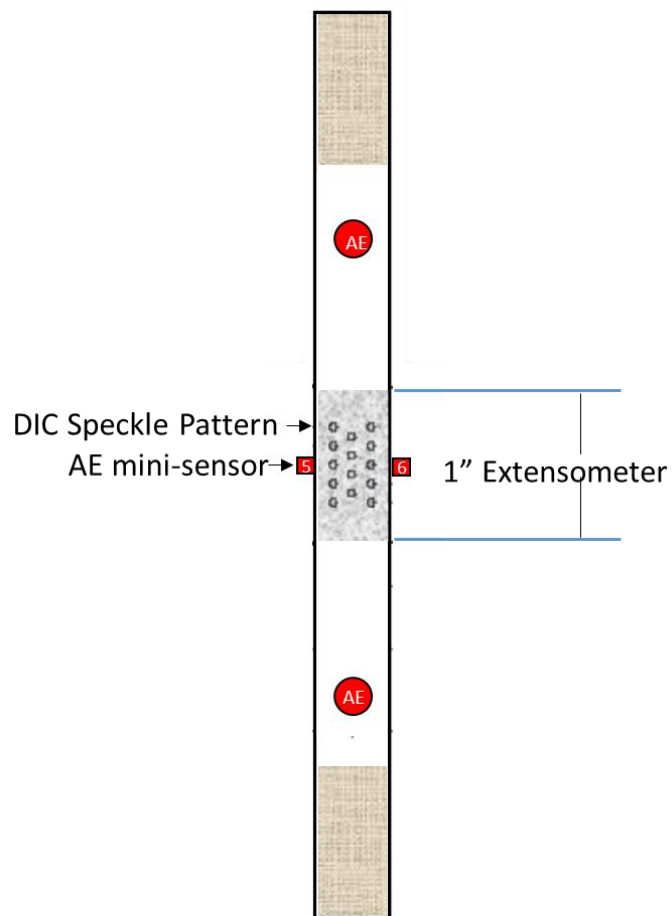
Ultrasonic Drilling



- Holes were machined by ultrasonic drill.
- Drilling was done after depositing EBC
- Diameters were typically 1.1 mm.
- Samples were prepared with holes oriented at either 90° or 30°, relative to the surface.
- 90° Holes were arranged in a 14 hole array.
 - Horizontal & vertical spacing = 3 x Diameter
- 30° Holes were arranged in a 3 hole array.
 - Representative of blade leading edge cooling holes

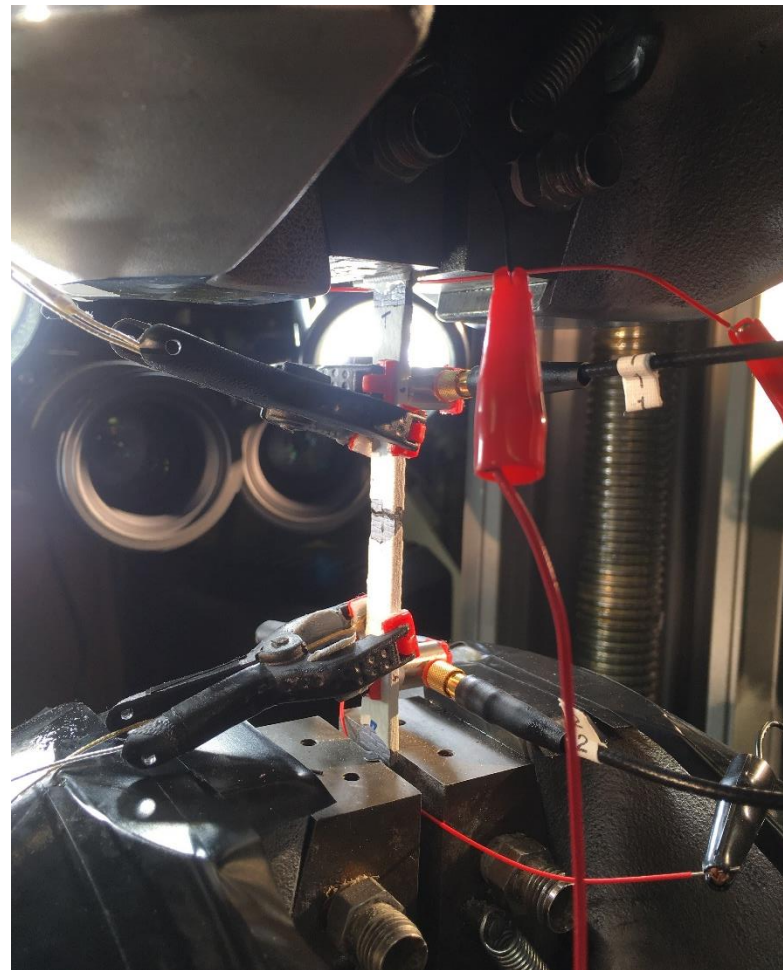
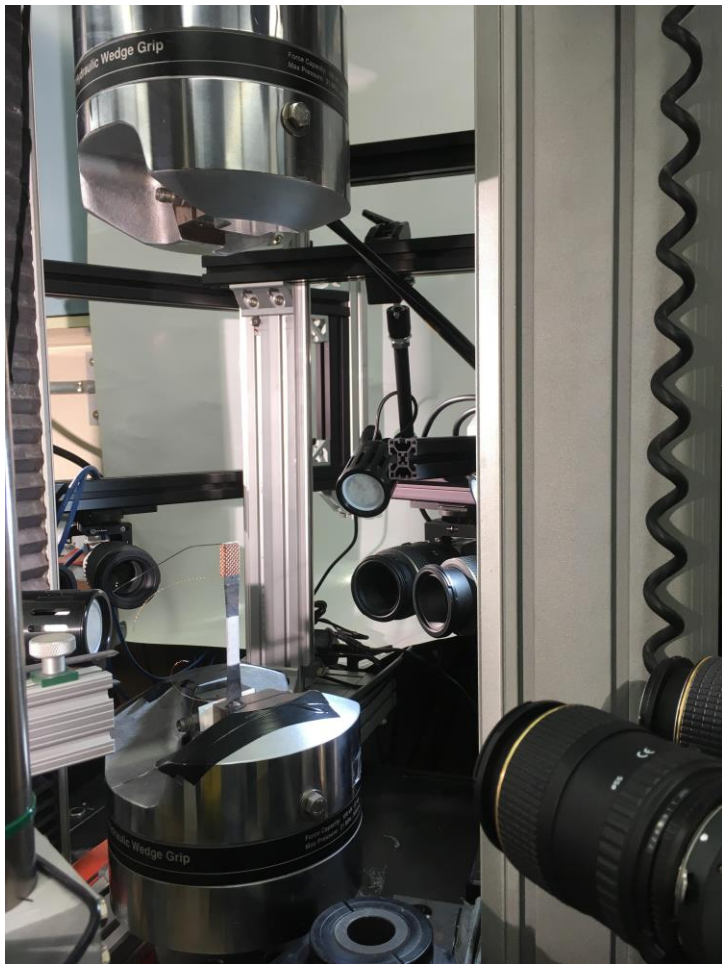


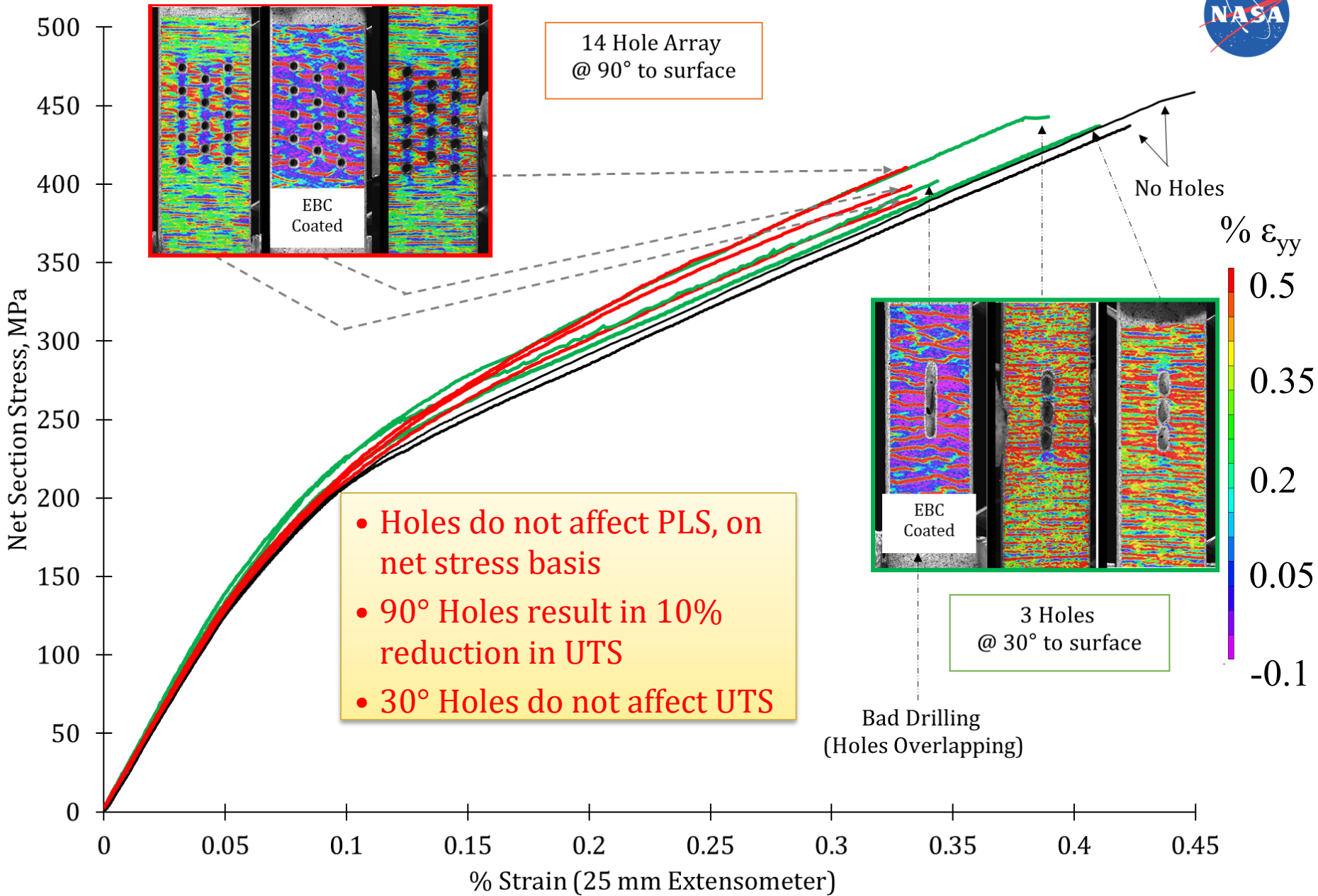
Diagnostic Tools

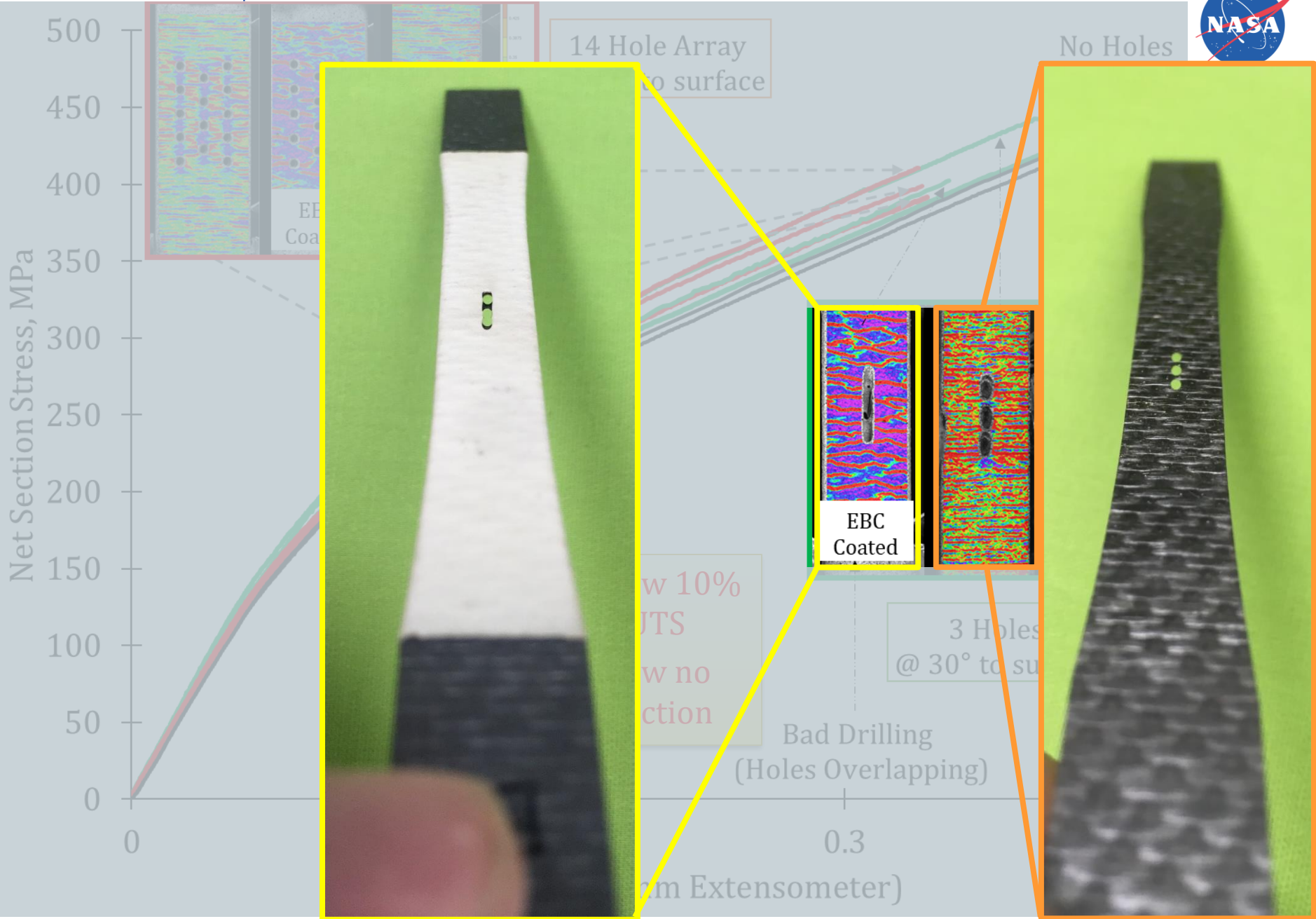


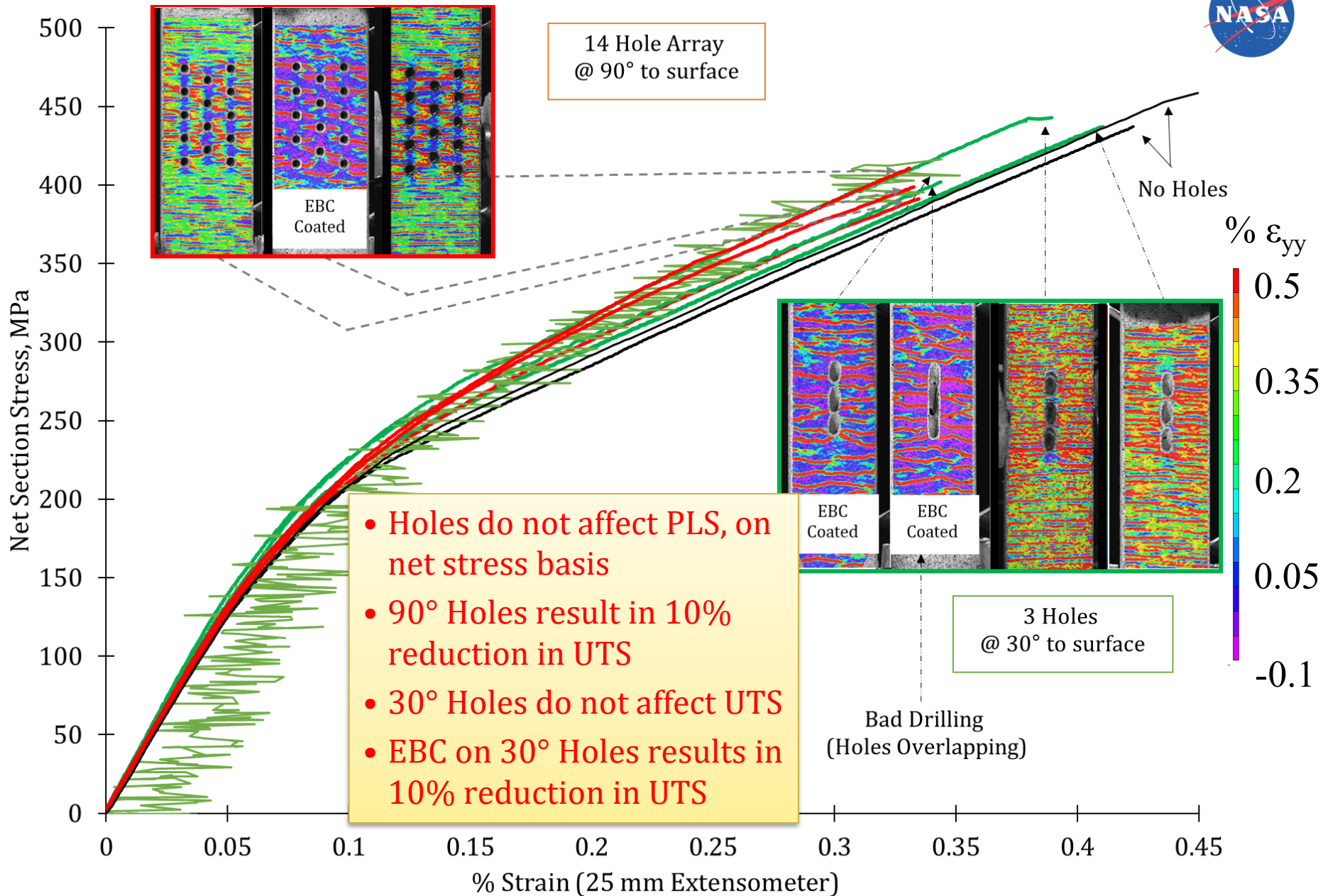
- Acoustic Emission (AE) sensors applied to face and edges
- 3D Digital Image Correlation (DIC)
- 1 inch extensometer on edge

Test Setup









DIC Strain of Un-Coated 90° Hole Array Sample

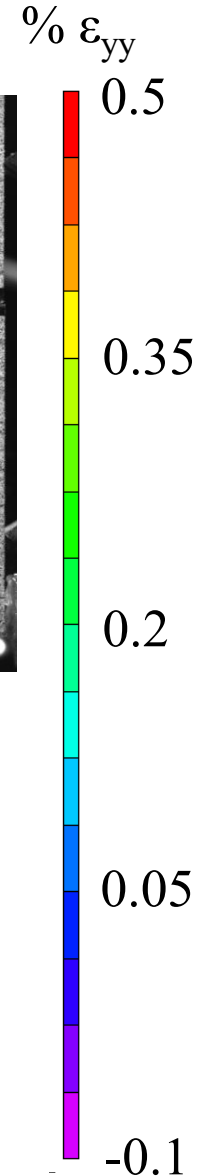
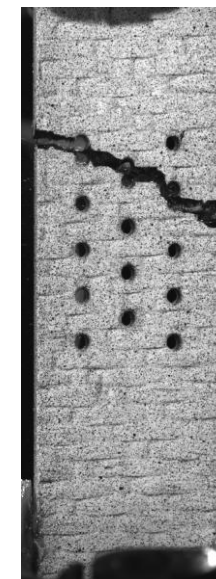
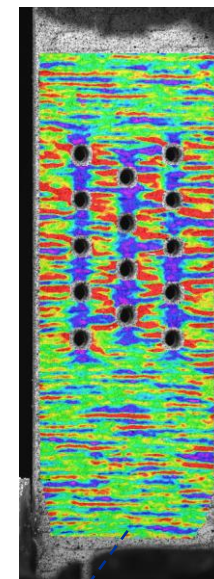
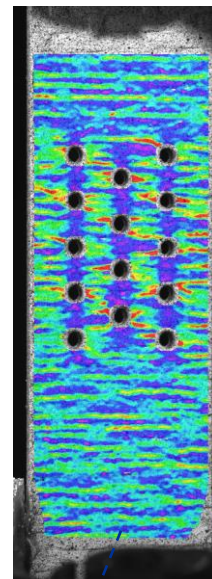
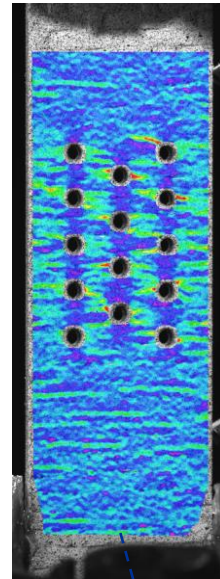
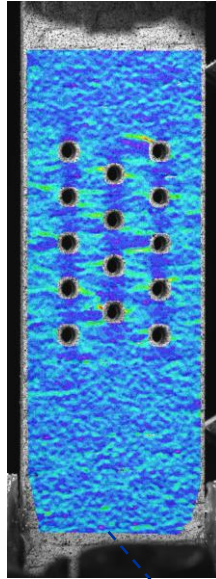
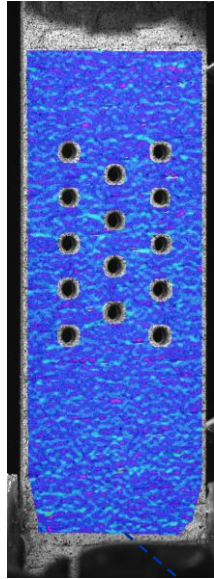
58 MPa

176 MPa

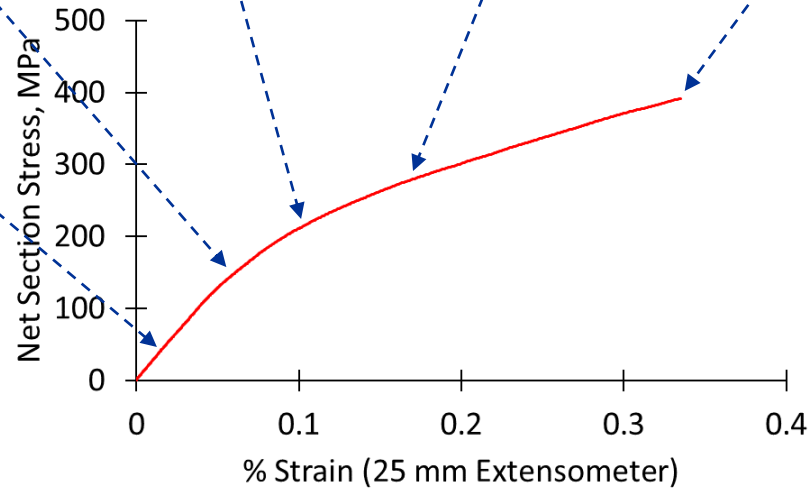
227 MPa

291 MPa

390 MPa

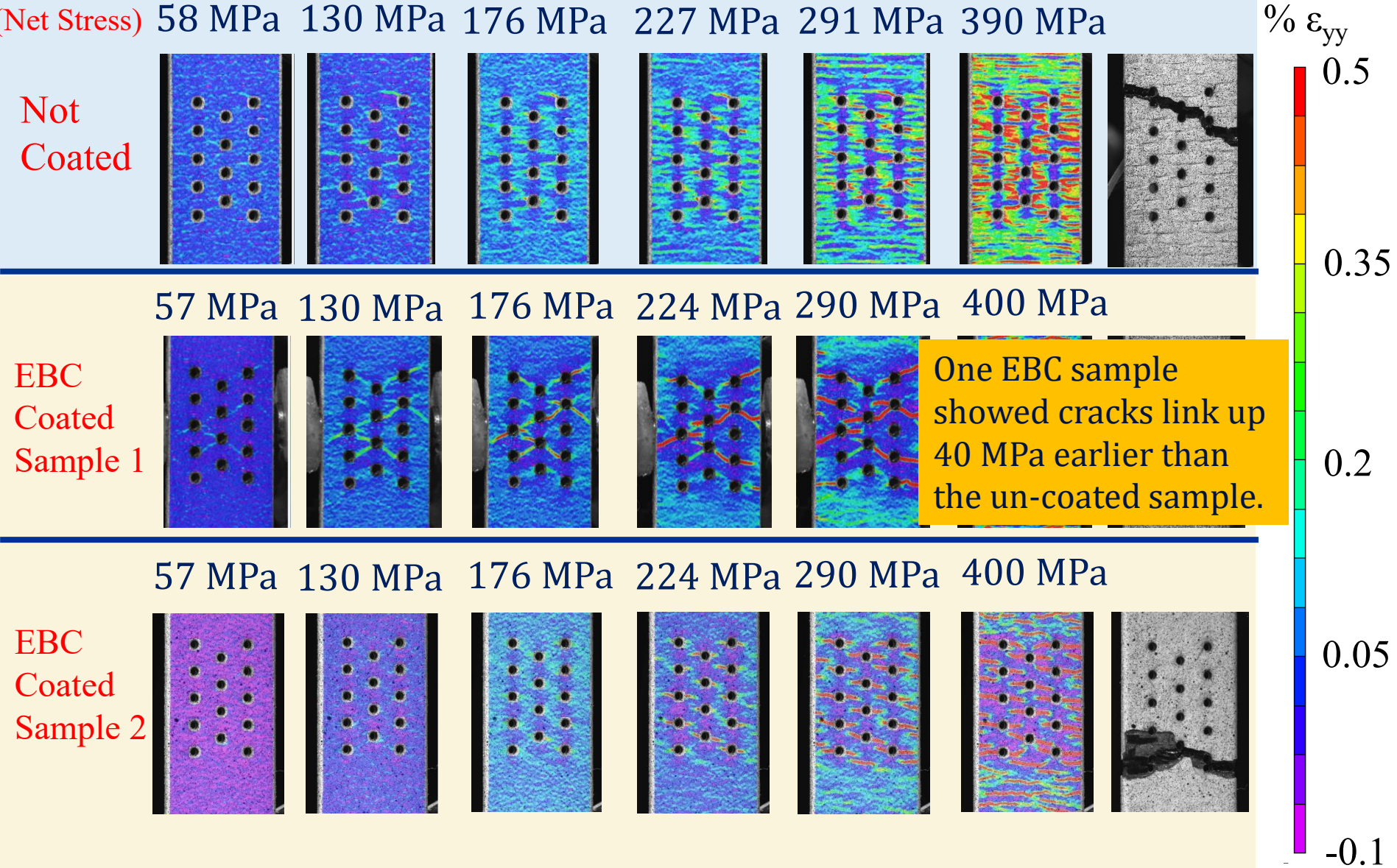


Strain accumulation observed near the holes at stresses well below the PLS.





DIC Strain of Un-Coated & EBC Coated 90° Hole Array Sample



DIC Strain of Un-Coated 30° Hole Sample

150 MPa

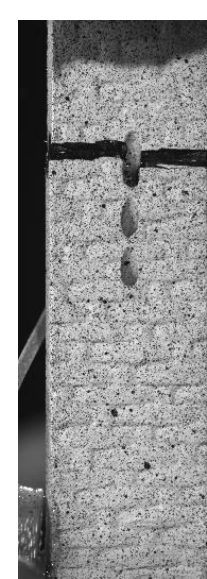
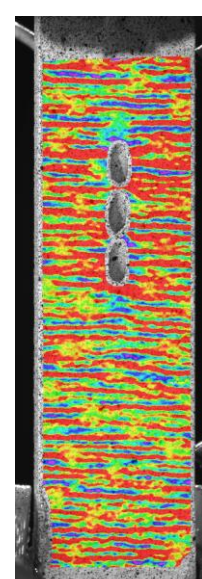
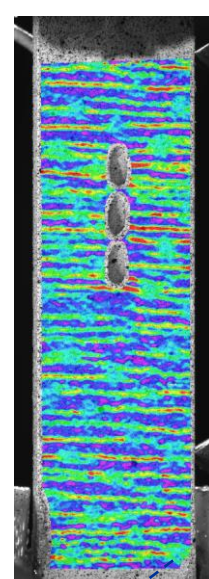
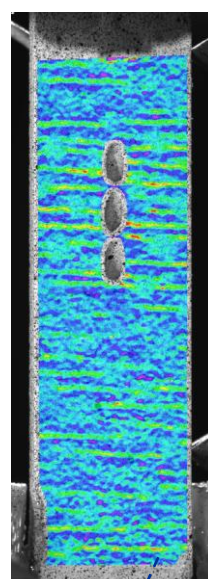
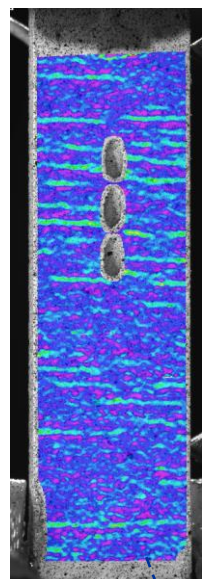
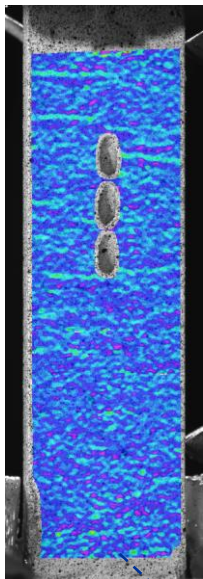
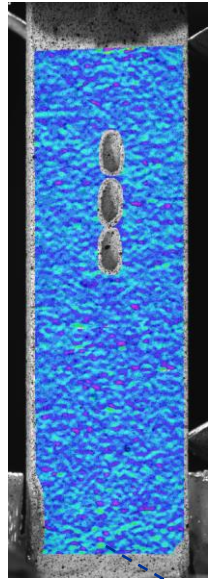
172 MPa

210 MPa

224 MPa

279 MPa

434 MPa

% ϵ_{yy}

0.5

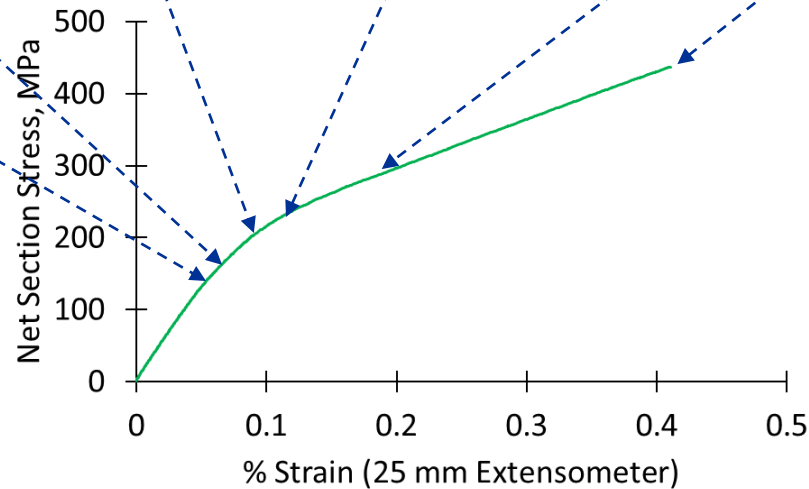
0.35

0.2

0.05

-0.1

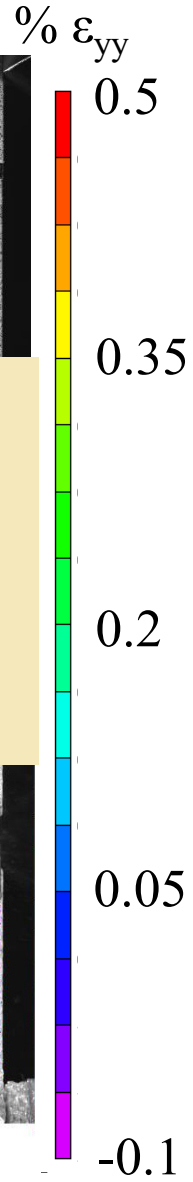
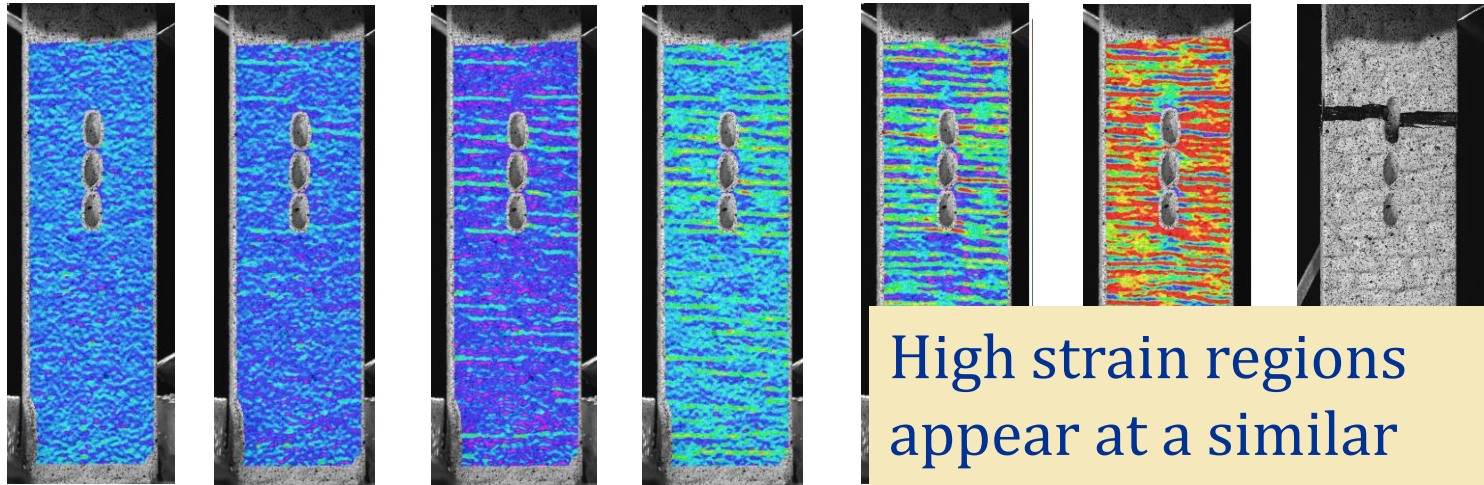
High strain regions appear in the far-field at the same time as the 30° holes.



DIC Strain of Un-Coated & Coated 30° Hole Sample

(Net Stress) 150 MPa 172 MPa 210 MPa 224 MPa 279 MPa 434 MPa

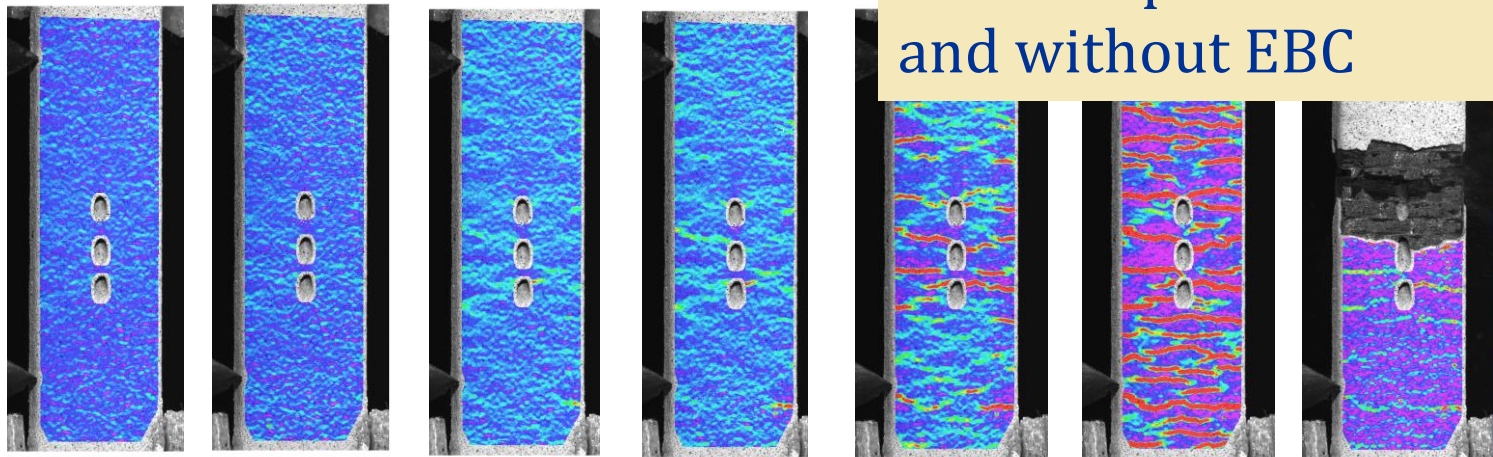
Not Coated



High strain regions appear at a similar net stress for 30° hole samples with and without EBC

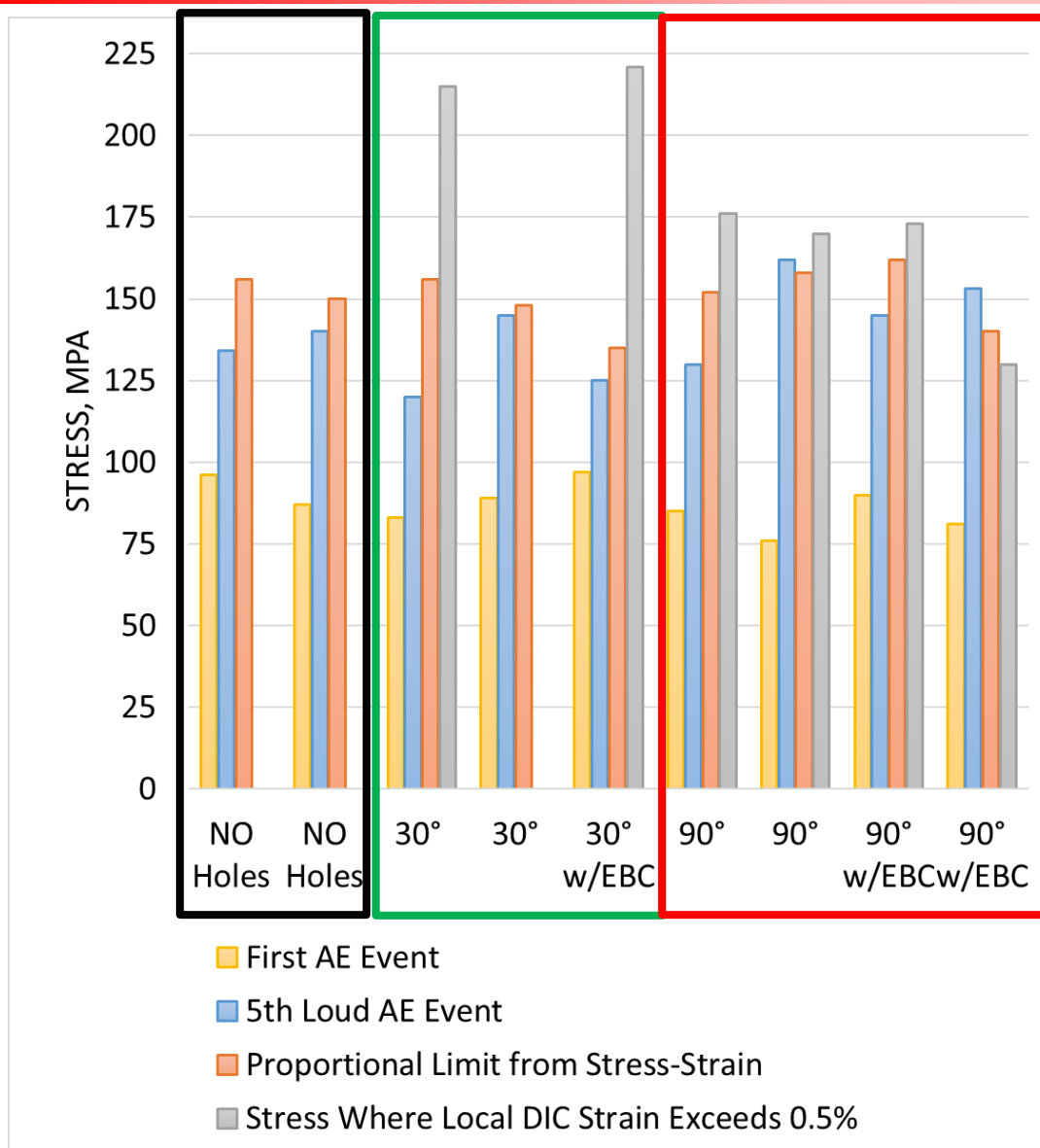
150 MPa 171 MPa 211 MPa 224 MPa 279 MPa 434 MPa

EBC Coated





Comparing the Beginning of Cracking



- All samples have similar PL and beginning of AE activity
- 90° samples reach local DIC strains of 0.5% at ~50 MPa lower stress than 30° samples



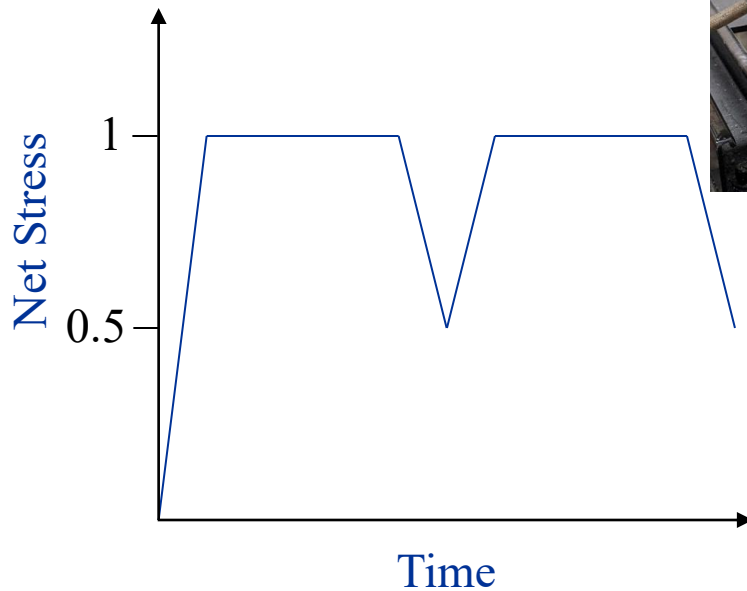
Room Temperature Results

- Holes do not affect proportional limit stress, on a net stress basis
 - DIC does show strain accumulation near 90° holes below the PLS
- Ultimate tensile strength is affected by hole angle
 - 90° Holes cause a 10% reduction in UTS
 - 30° Holes do not affect UTS
 - However, 30° Holes with EBC cause a 10% reduction in UTS

Durability Testing

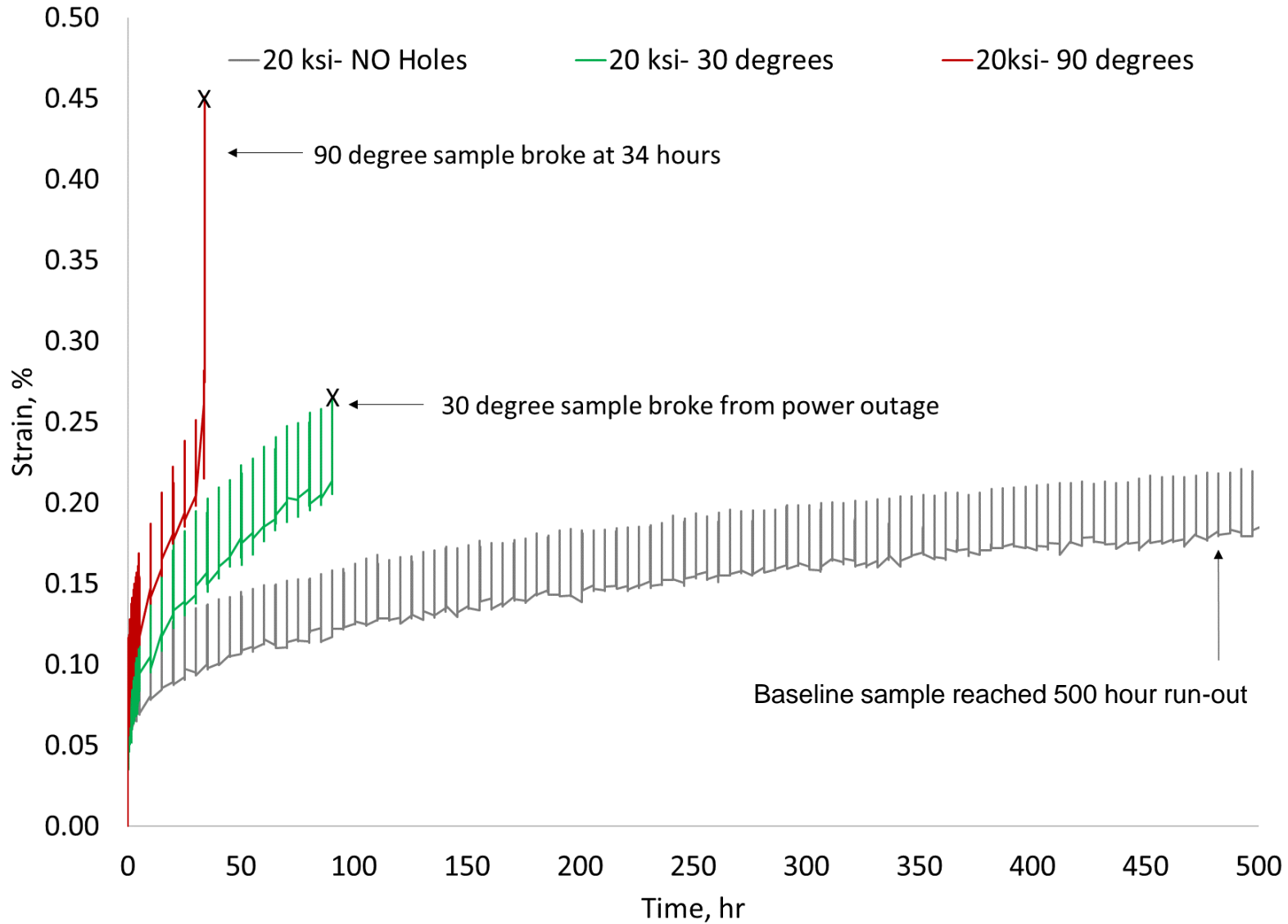
Sustained Peak Low Cycle Fatigue Tests (SPLCF) were done in air

- 1315°C
- R=0.5
- 30 second ramp
- 2-minute dwell



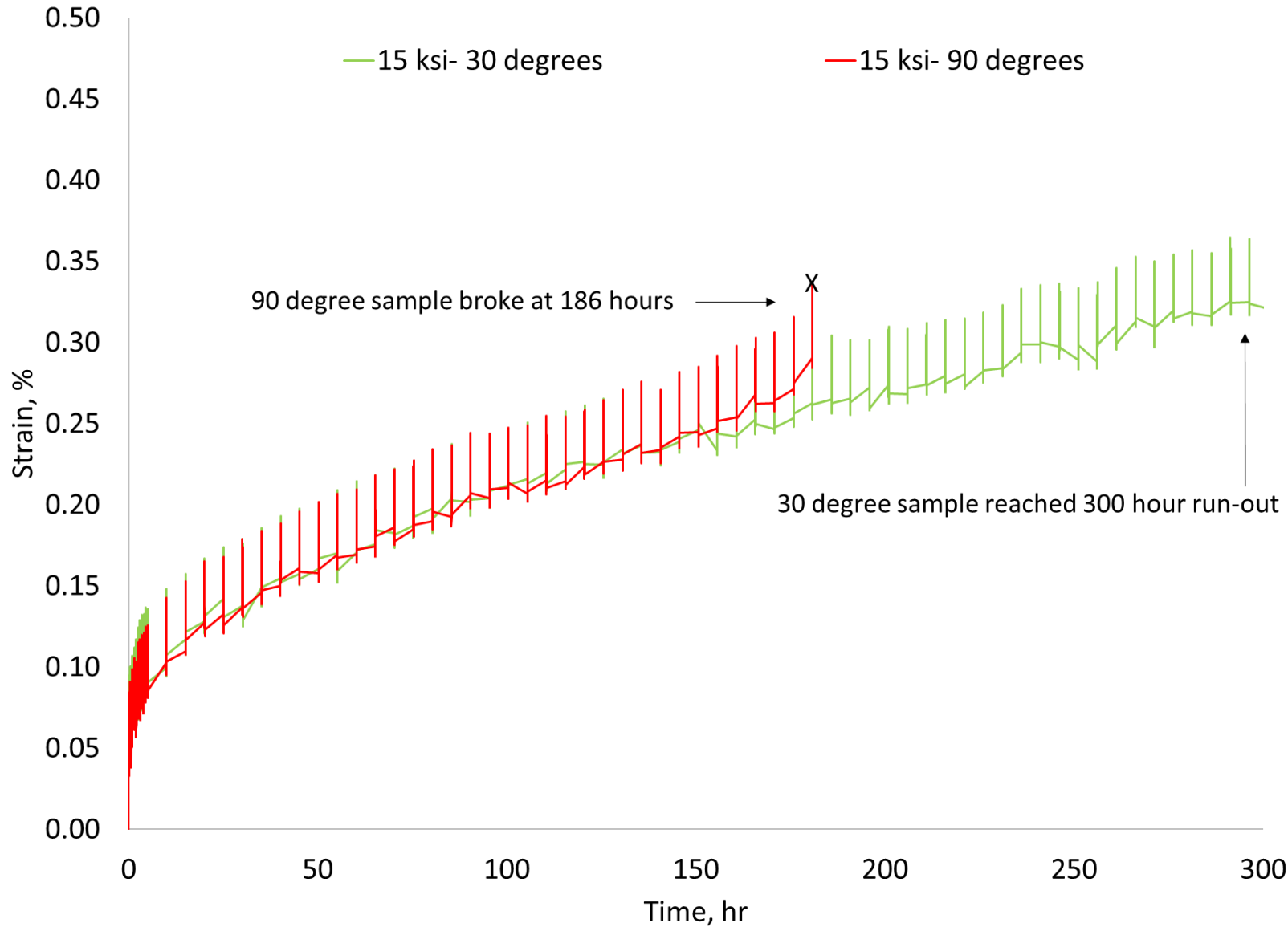


SPLCF Testing – 20 ksi (138 MPa) Dwell



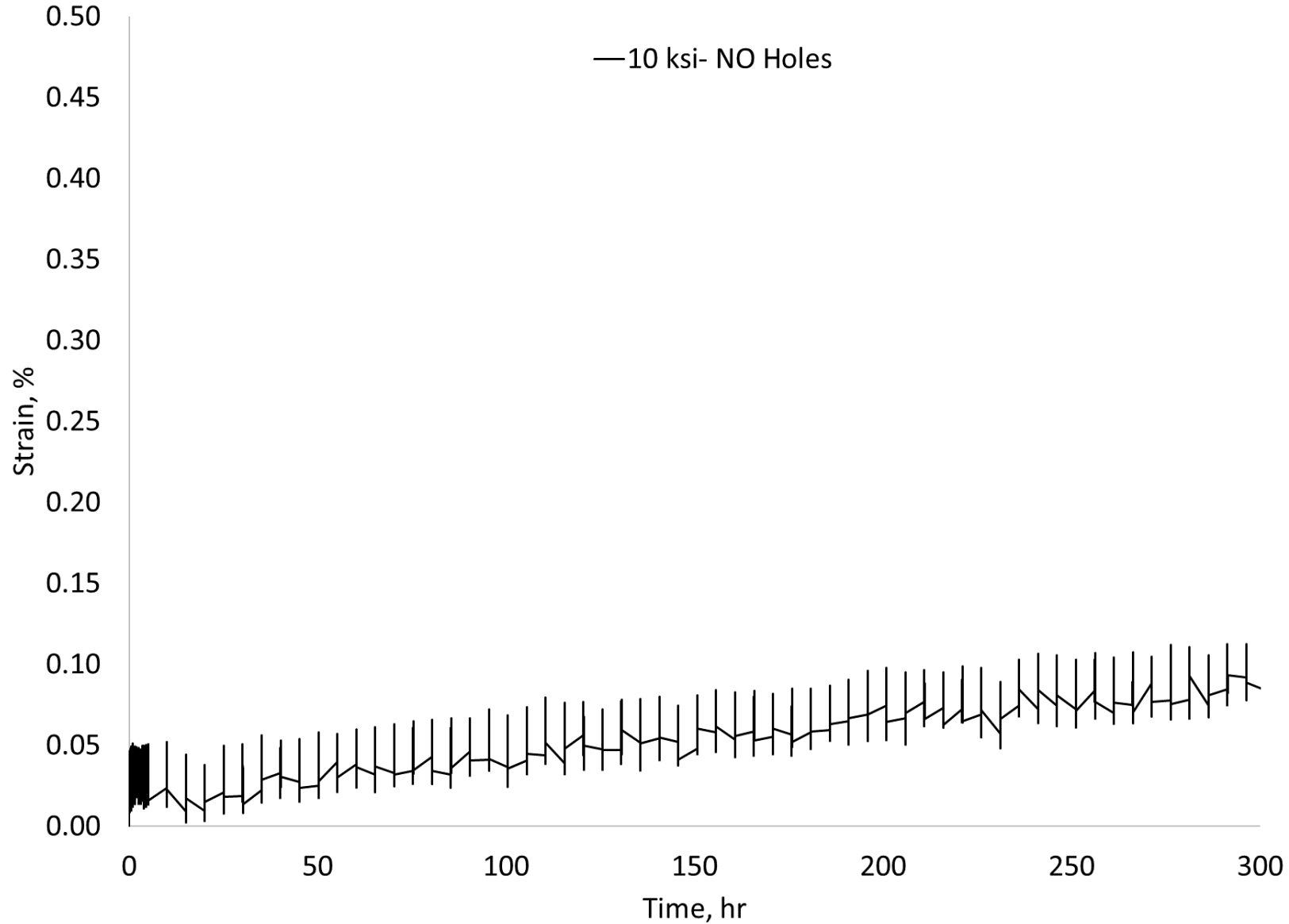


SPLCF Testing – 15 ksi (103 MPa) Dwell



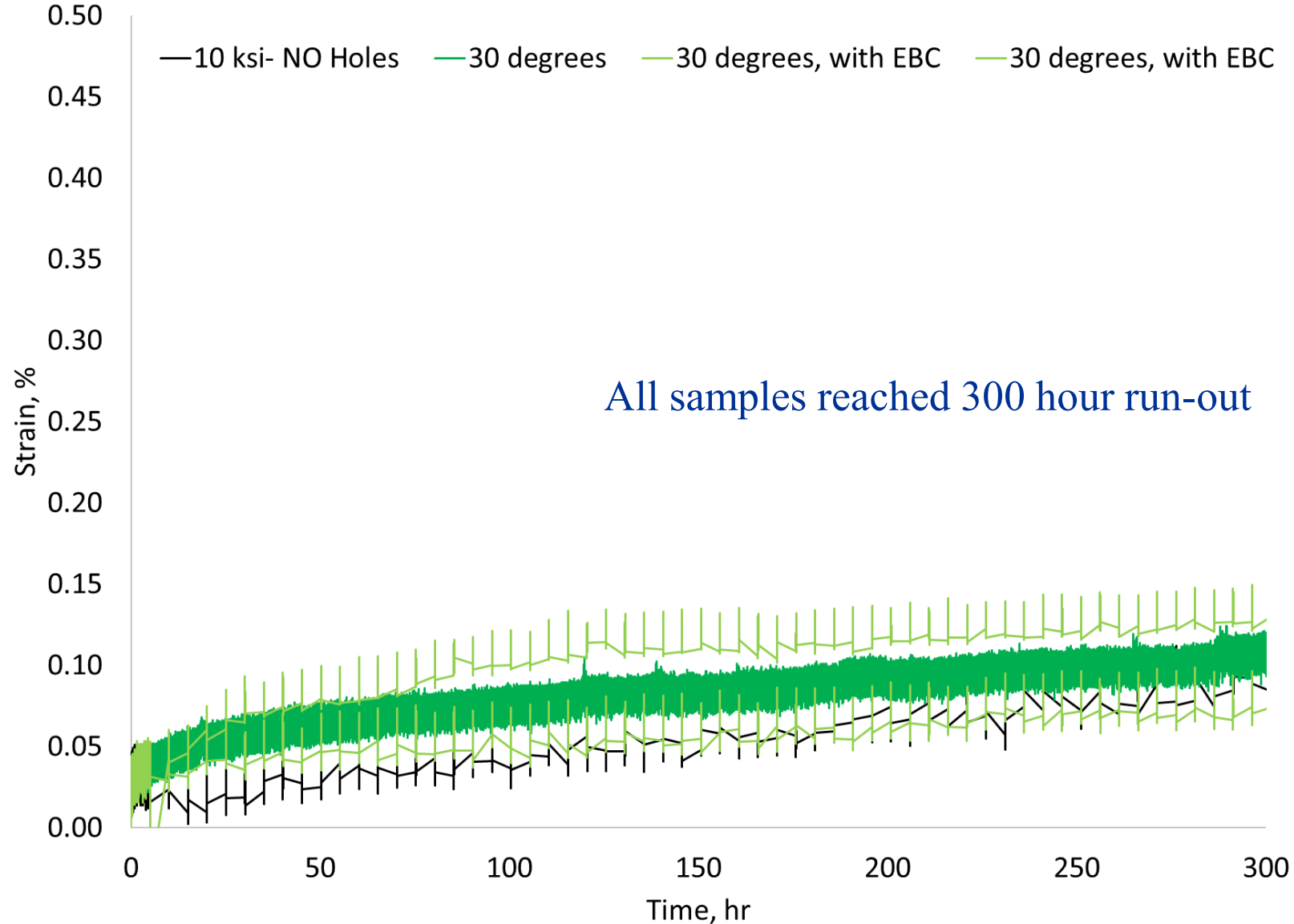


SPLCF Testing – 10 ksi (69 MPa) Dwell



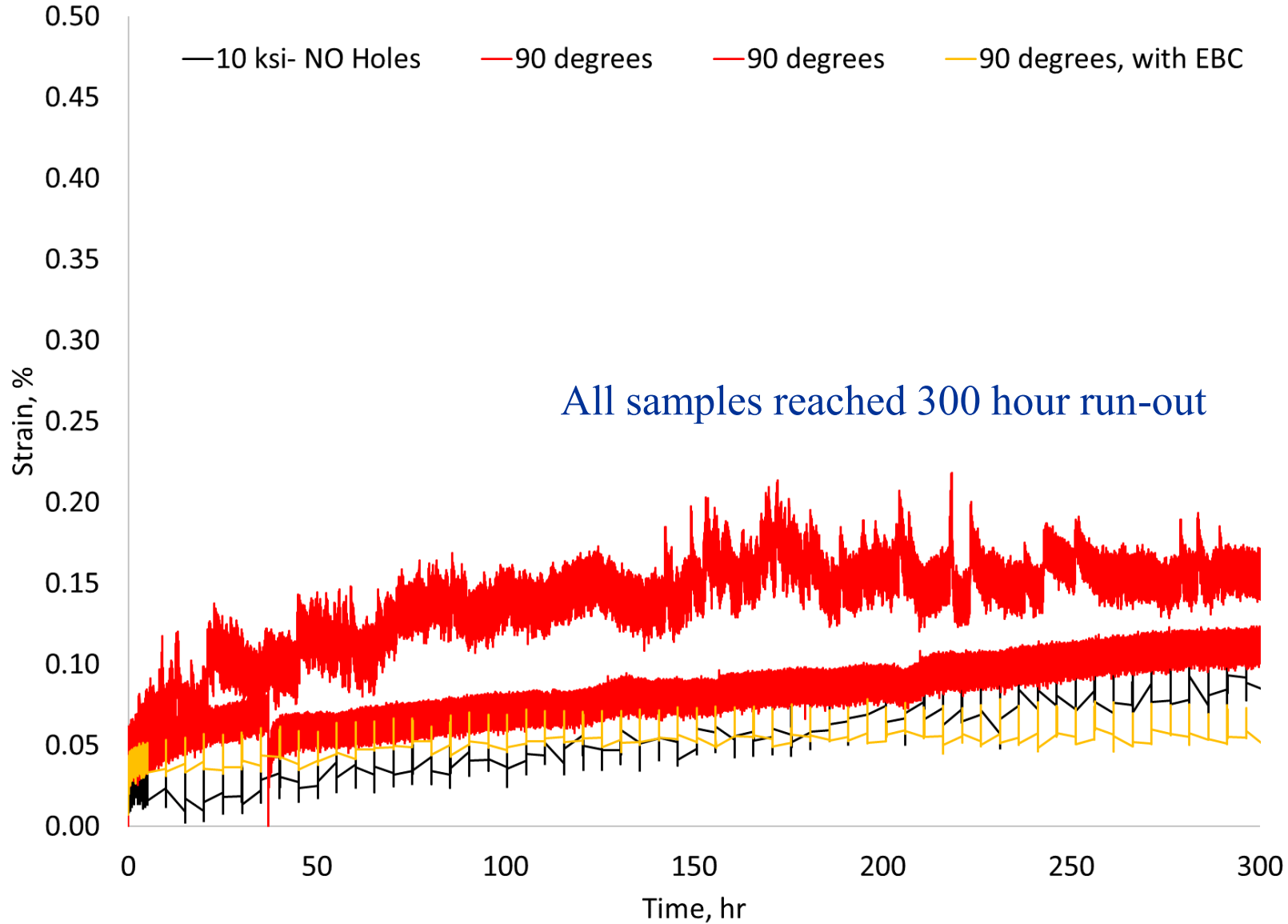


SPLCF Testing – 10 ksi (69 MPa) Dwell

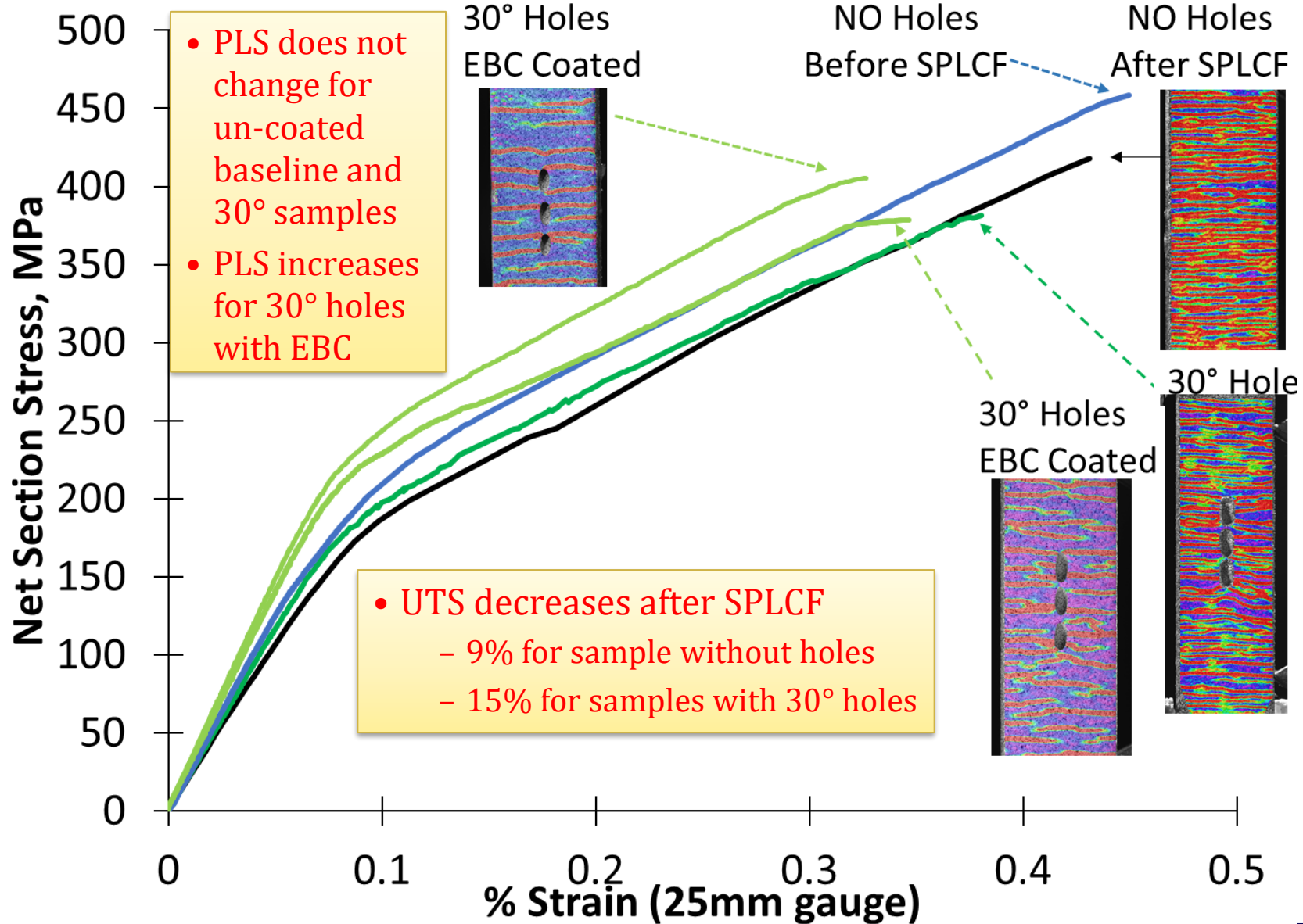




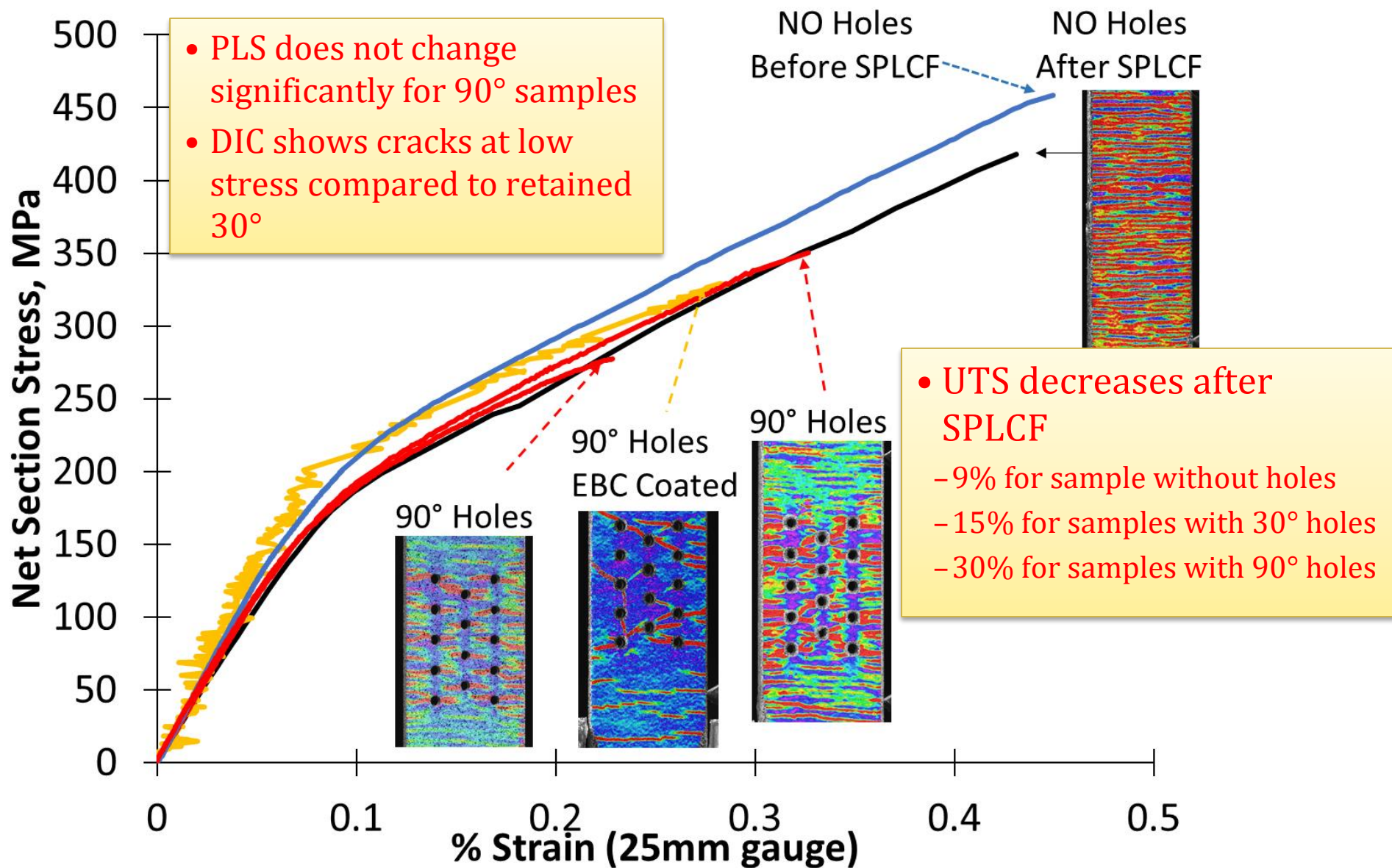
SPLCF Testing – 10 ksi (69 MPa) Dwell



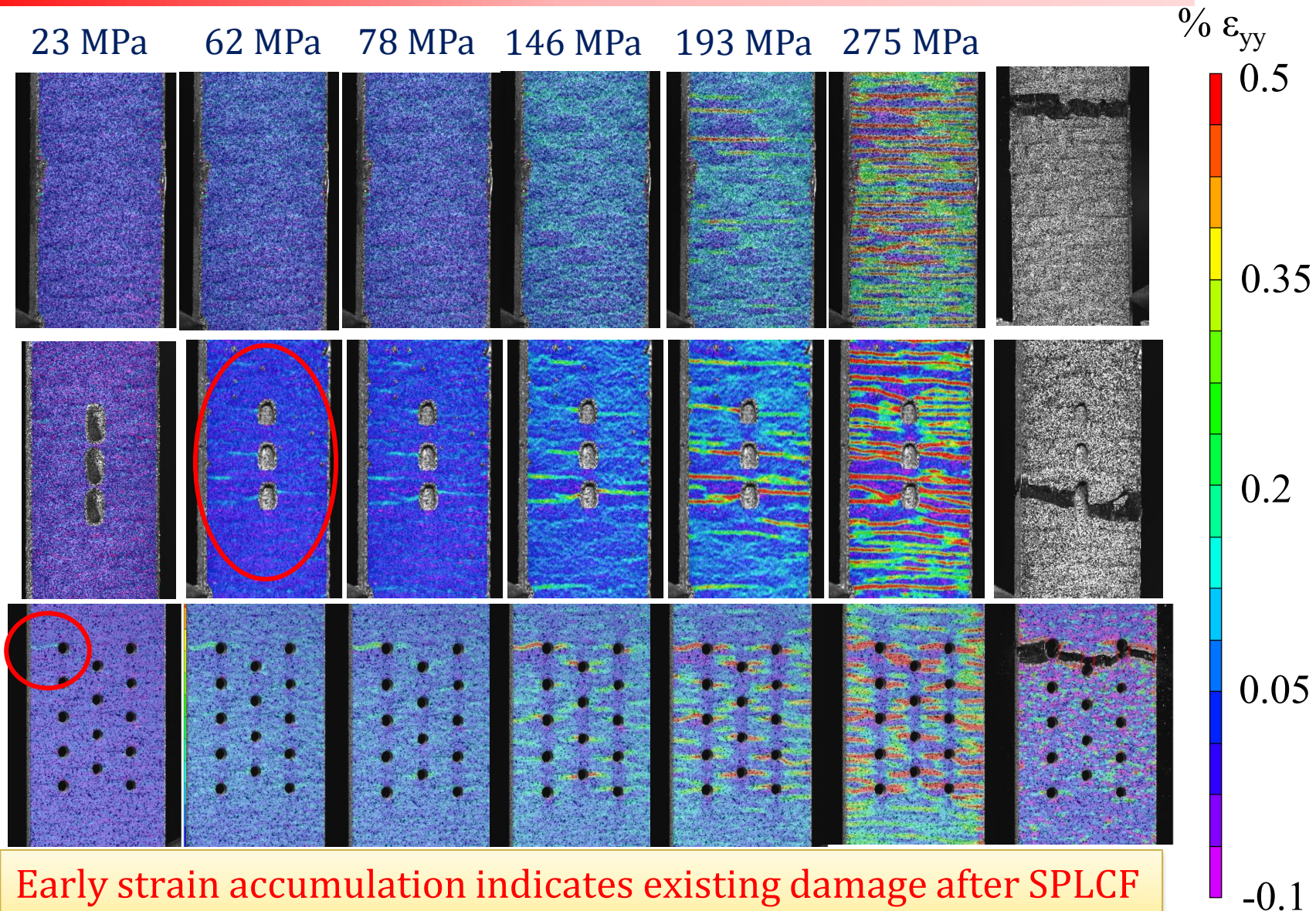
Retained Strength after SPLCF Testing at 69 MPa Dwell



Retained Strength after SPLCF Testing at 69 MPa Dwell

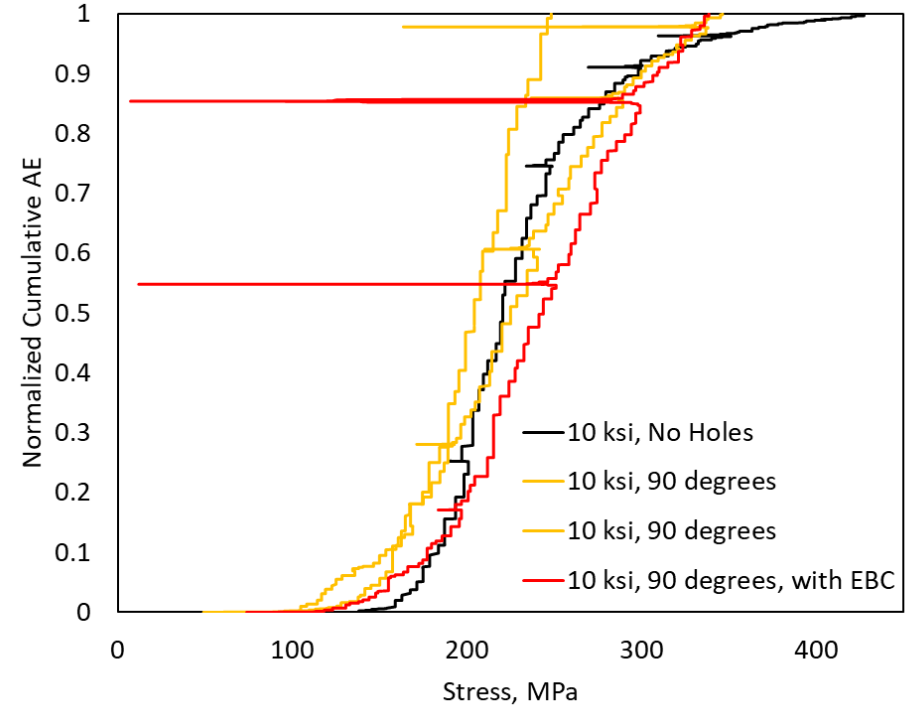
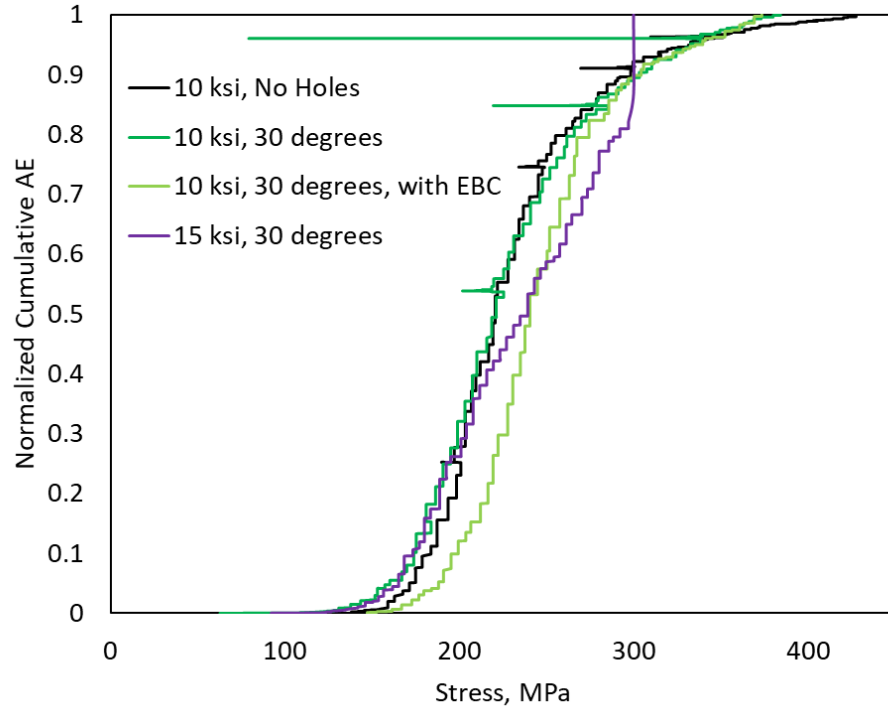


DIC Strain of Un-Coated Samples after 69 MPa SPLCF





Acoustic Emission after 10 ksi (69 MPa) SPLCF



90° samples start cracking at lower stress



Summary

- MI SiC/SiC samples with multiple holes were tensile tested.
- Room Temperature Results:
 - Holes do not affect proportional limit stress, on a net stress basis
 - DIC does show strain accumulation near 90° holes below the PLS
 - Ultimate Tensile Strength is affected by hole angle
 - Zero Reduction for 30° holes
 - 10% Reduction for 90° holes
 - However, 30° Holes with EBC cause a 10% reduction in UTS
- SPLCF Results:
 - 90° Holes lead to reduced life compared to 30° Holes or baseline samples
 - Proportional Limit Stress is largely unaffected by holes
 - EBC on 30° holes led to an increase in PLS after SPLCF
 - Ultimate Tensile Strength decreases after 300-hour SPLCF at 69 MPa
 - 9% Reduction for the sample without holes
 - 15% Reduction for samples with 30° holes
 - 30% Reduction for samples with 90° holes



Acknowledgements

- Kang Lee, NASA GRC
- Dan Gorican, HX5 LLC